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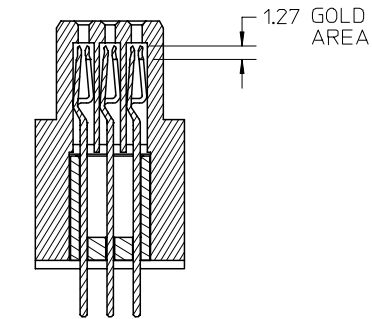
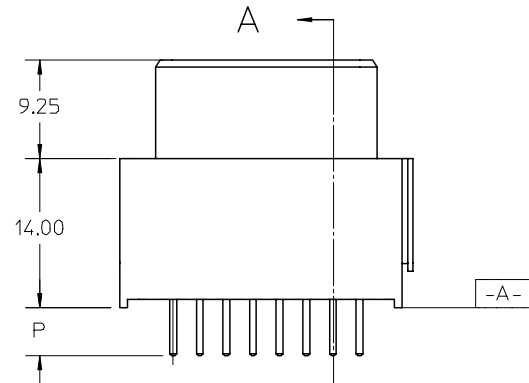
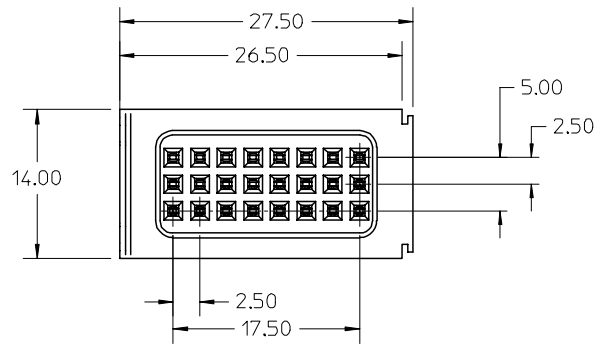
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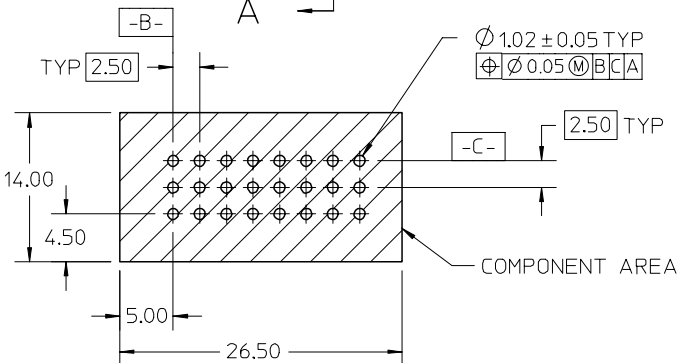
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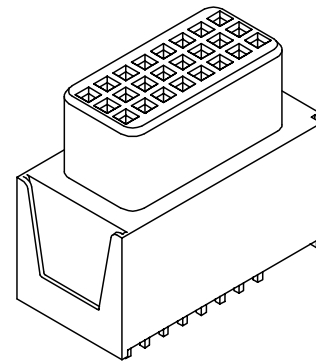


SECTION A-A



PCB LAYOUT: COMPONENT SIDE
PCB TOLERANCE: ±0.05

- NOTES:
- HOUSING MATERIAL: LCP, 30% GLASS FILLED, UL94V-0, BLACK
TERMINAL MATERIAL: COPPER ALLOY - C7026 (TMOS)
BLADE MATERIAL: COPPER ALLOY - C110
 - FINISH: SELECT GOLD: 30 MI MIN
SELECT TIN: 150 / 250 MI
BOTH OVER NICKEL: 50 MI MIN
 - PRODUCT SPECIFICATION: PS-45424-001
 - PACKAGING SPECIFICATION: ES-45483-999
 - PRODUCT AND/OR PROCESS CHANGES MUST BE APPROVED BY MOLEX ENGINEERING PRIOR TO IMPLEMENTATION.
 - DIMENSIONS GIVEN ACROSS CENTERLINES ARE SYMMETRICAL ABOUT THOSE CENTERLINES WITHIN HALF THE TOTAL TOLERANCE.
 - TERMINAL RETENTION IN HOUSING: 2.5 LBS MIN.
 - THIS MODULE MUST INTERLOCK WITH ALL STANDARD MOLEX POWER DOCK MODULES.
 - PART IS RoHS COMPLIANT. SEE ES-45483-999 FOR LABEL REQUIREMENTS.



PCB THICKNESS	DIM P	MATERIAL NUMBER
.125 3.18	.177 4.50	45515-0001
.093 2.36	.143 3.60	45515-0002
.062 1.57	.115 2.92	45515-0003

STANDARDIZATION EC NO: UCP2005-1675 DRWN:KSAMIEC 2005/11/29 CHKD:KSAMIEC 2005/11/29 APPR:APATEL 2005/12/12 DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1.5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		mm	INCH	DRAWN BY SCHAFFER	DATE 2005/2/17	TITLE POWER DOCK MODULE SIGNAL SOCKET 24 PIN VERTICAL SOLDER TAIL	
	4 PLACES	± ---	± ---	CHECKED BY SAMIEC	DATE 2005/2/8		
	3 PLACES	± ---	± ---	APPROVED BY MARGULIS	DATE 2005/2/9	MOLEX INCORPORATED DOCUMENT NO. SD-45515-001	
	2 PLACES	± 0.15	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			
1 PLACE	± 0.25	± ---	SIZE A		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

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